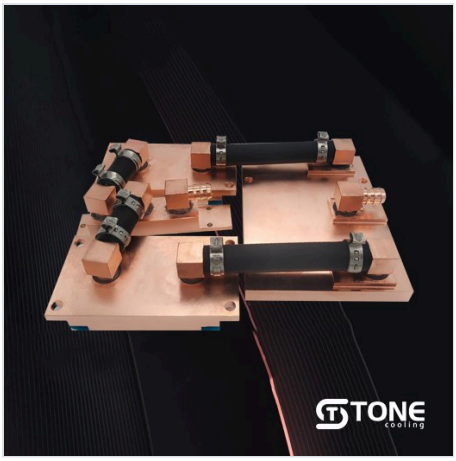
NVIDIA GB200 Superchip Liquid Cold Plate

Model T-HS202324 · NVIDIA GPU + CPU · 2 × 1500 W GPU + 200 W CPU · Copper, TLP

Rated heat load	Max. surface temp.	Flow / pressure drop	Total height
1500 W × 2 + 200 W	<55°C	4.4 LPM / 30 kPa	31 mm



T-HS202324

Integrated copper cold plate module for the NVIDIA GB200 Grace Blackwell Superchip — two Blackwell GPUs and the Grace CPU cooled by one assembly, 152.9 × 194 × 31 mm. Removes 3.2 kW with pure water at 4.4 LPM / 30 kPa and 25 °C inlet, holding contact surfaces below 55 °C. Rated 0.6 MPa for tray-level manifold systems.

Performance & mechanical data

Parameter	Value
Rated heat load	1500 W × 2 + 200 W
Coolant (as tested)	Pure water
Inlet coolant temperature	25 °C
Max. plate surface temperature	< 55 °C
Flow rate / pressure drop	4.4 LPM / 30 kPa
Working pressure rating	0.6 MPa
Dimensions (L × W × H)	152.9 × 194 × 31 mm

Construction

Parameter	Value
Base material	Copper
Bonding process	TLP — Transient Liquid-Phase Diffusion Bonding
Working pressure rating	0.6 MPa
Coolant compatibility	Water / EGW / PGW mixtures (validated as listed)
Fittings & port position	Per drawing; customisable on request
Leak test	100% pressure-tested before shipment

Typical applications

- GB200 NVL72 / NVL36 compute trays
- Next-generation AI factory racks
- OEM / ODM liquid-cooled server platforms

Ordering & RFQ

How to order: quote model T-HS202324 with quantity and required fitting type.

RFQ checklist: target device / PCB, quantity, coolant type, inlet temperature, target flow rate, mechanical envelope.

Contact: www.tonecooling.com · sales@tonecooling.com

Performance values are typical results at the stated coolant, inlet temperature and flow rate; surface temperature is measured at the device contact area. TIM and mounting pressure affect final junction temperature. Specifications subject to change without notice. Third-party product names are trademarks of their respective owners and are used for compatibility reference only.